

**Product / Package Information**

<b>Package</b>	LFCSP - Sawn
<b>Body Size (mm)</b>	3 X 3 X 1.45 (1.6EP)
<b>Lead Count</b>	16
<b>Terminal Finish</b>	100 Sn

**Environmental Information**

<b>RoHS Compliant</b>	Yes with exemption
<b>High Temperature Compliant</b>	Yes
<b>Halogen Free Compliant</b>	Yes
<b>REACH SVHC Compliant</b>	Yes

**Materials Declaration**

**Molding Compound**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	1.89E-02	93.7	937000	49.96	499558
Thermosets	Epoxy resin	Proprietary	6.05E-04	3.0	30000	1.60	15994
Thermosets	Phenol resin	Proprietary	6.05E-04	3.0	30000	1.60	15994
Other inorganic materials	Carbon black	1333-86-4	6.05E-05	0.3	3000	0.16	1599
<b>Subtotal</b>			<b>2.02E-02</b>	<b>100.00</b>	<b>1000000</b>	<b>53.31</b>	<b>533146</b>

**Leadframe**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	9.68 E-03	96.20	962000	25.61	256061
Copper & its alloys	Nickel	7440-02-0	3.02 E-04	3.00	30000	0.80	7985
Copper & its alloys	Silicon	7440-21-3	6.54 E-05	0.65	6500	0.17	1730
Copper & its alloys	Magnesium	7439-95-4	1.51 E-05	0.15	1500	0.04	393
<b>Subtotal</b>			<b>1.01 E-02</b>	<b>100.00</b>	<b>1000000</b>	<b>26.62</b>	<b>266176</b>

**Internal Leadframe Plating**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.90 E-04	100.0	1000000	0.50	5027

**External Leadframe Plating**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	4.50 E-04	100.0	1000000	1.19	11906

**Bond Wires**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	5.94 E-05	99.0	990000	0.16	1572
Precious metals	Palladium	7440-05-3	6.00 E-07	1.00	10000	0.002	16
<b>Subtotal</b>			<b>6.00 E-05</b>	<b>100.0</b>	<b>1000000</b>	<b>0.16</b>	<b>1588</b>

**Chip**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	4.99 E-03	100.0	1000000	13.20	132030

**Die Attach**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Thermoset	Resin	Proprietary	5.86 E-04	58	580000	1.55	15500
Other organic materials	Polytetrafluoroethylene	9002-84-0	4.24 E-04	42	420000	1.12	11224
<b>Subtotal</b>			<b>1.01 E-03</b>	<b>100.0</b>	<b>1000000</b>	<b>2.67</b>	<b>26723</b>

**Seal Glass**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Ceramics/Glass	Lead borosilicate glass	65997-17-3	7.74 E-04	87.5	875000	2.05	20478
Ceramics/Glass	Aluminosilicate glass	65997-17-3	1.11 E-04	12.5	125000	0.29	2925
			8.85 E-04			2.34	23403

<b>Package Totals</b>			<b>3.78 E-02</b>			<b>100</b>	<b>1000000</b>
-----------------------	--	--	------------------	--	--	------------	----------------

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



ADI Proprietary